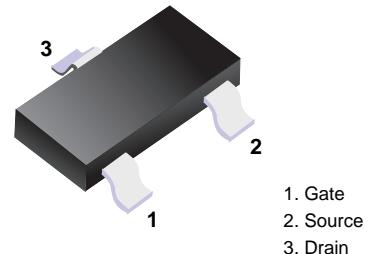


■ Features

- Halogen and Antimony Free
- Depletion Mode
- ESD Improved Capability


■ Simplified outline(SOT-23)
■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DSX}	600	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current	I _D	0.03	
Continuous Drain Current T _C =70°C		0.024	A
Pulsed Drain Current	I _{DM}	0.12	
Power Dissipation	P _D	0.5	W
Gate Source ESD (HBM-C=100pF, R=1.5kΩ)	V _{ESD(G-S)}	300	V
Junction Temperature	T _J	150	°C
Storage Temperature Range	T _{STG}	-55 to 150	°C
Thermal Characteristics			
Parameter	Symbol	Typ.	Units
Maximum Junction-to-Ambient	R _{θJA}	250	°C/W

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSX}	V _{GS} = -5V, I _D = 250µA	600	-	-	V
Gate Leakage Current	I _{GSS}	V _{GS} = ±10V	-	-	±100	nA
Off-state Drain to Source Current	I _{D(off)}	V _{DS} = 600V, V _{GS} = -5V	-	-	0.1	µA
		V _{DS} = 480V, V _{GS} = -5V, T _a =125 °C	-	-	10	µA
ON Characteristics						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = 3V, I _D = 8µA	-2.7	-1.8	-1	V
On-state drain current	I _{DSS}	V _{GS} = 0V, V _{DS} = 25V	12	-	-	mA
Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} = 0V, I _D = 3mA	-	350	700	Ω
		V _{GS} = 10V, I _D = 16mA	-	400	800	
Dynamic Characteristics						
Forward transconductance	g _{fS}	V _{DS} = 50V, I _D = 0.01A	8	17	-	mS
Input Capacitance	C _{iss}	V _{DS} = 25V, V _{GS} = -5V, f = 1MHz	-	50	-	pF
Output Capacitance	C _{oss}		-	4.53	-	
Reverse Transfer Capacitance	C _{rss}		-	1.08	-	
Switching Characteristics						
Turn-On Delay Time	t _{d(on)}	V _{DD} =300V, V _{GS} =-5...7V R _G =6Ω, I _D =0.01A	-	9.9	-	ns
Turn-On Rise Time	t _r		-	55.8	-	
Turn-Off Delay Time	t _{d(off)}		-	56.4	-	
Turn-Off Fall Time	t _f		-	136	-	
Total Gate Charge	Q _g	V _{DD} =400V, V _{GS} =-5V to 5V, I _D =0.01A	-	1.14	-	nC
Gate-Source Charge	Q _{gs}		-	0.5	-	
Gate-Drain Charge	Q _{gd}		-	0.37	-	
Drain-source Diode Characteristics						
Diode Forward Current	I _S	T _a =25°C	-	-	0.025	A
Pulse Diode Forward Current	I _{SM}		-	-	0.1	A
Forward Diode Voltage	V _{SD}	V _{GS} = -5V, I _F = 16mA	-	-	1.2	V
Gate-source Zener diode						
Gate-source breakdown voltage	V _{GSO}	I _{GS} = ±1mA (Open Drain)	20	-	-	V

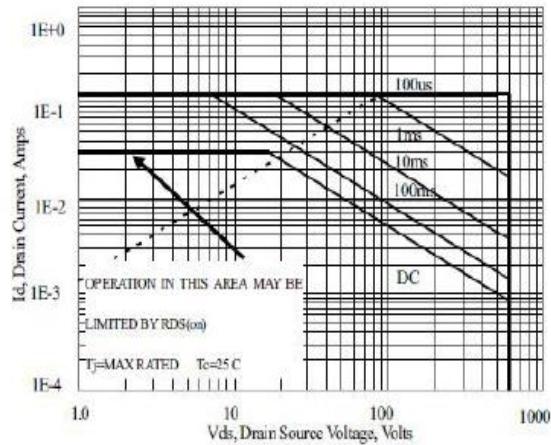


Figure 1 Maximum Forward Bias Safe Operating Area

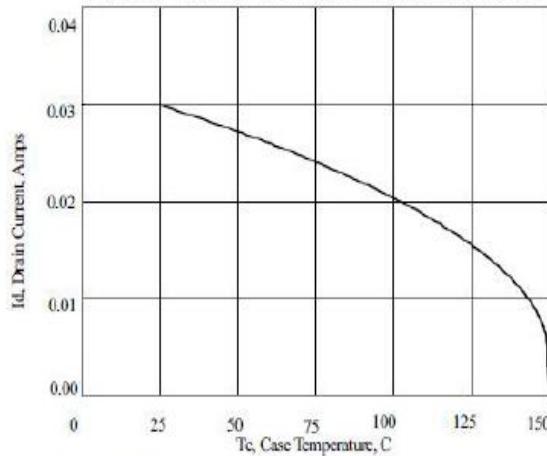


Figure 3 Maximum Continuous Drain Current vs Case Temperature

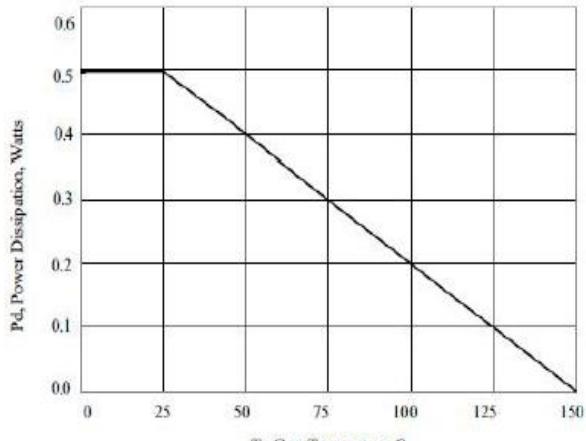


Figure 2 Maximum Power Dissipation vs Case Temperature

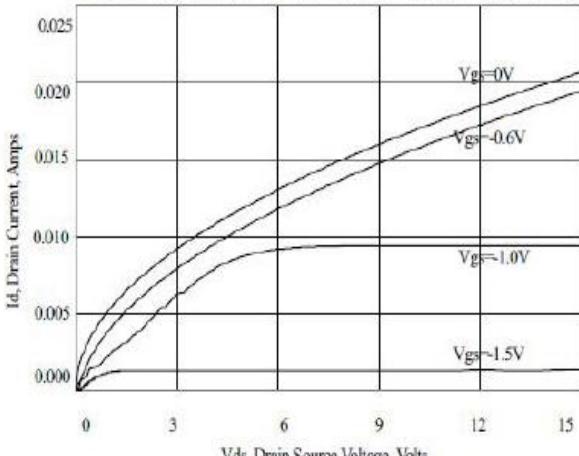


Figure 4 Typical Output Characteristics

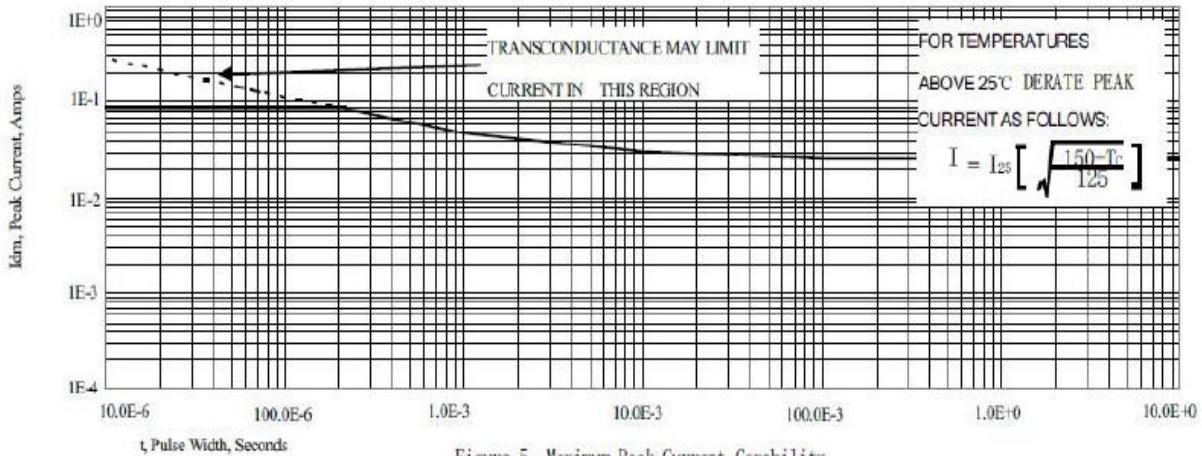


Figure 5 Maximum Peak Current Capability

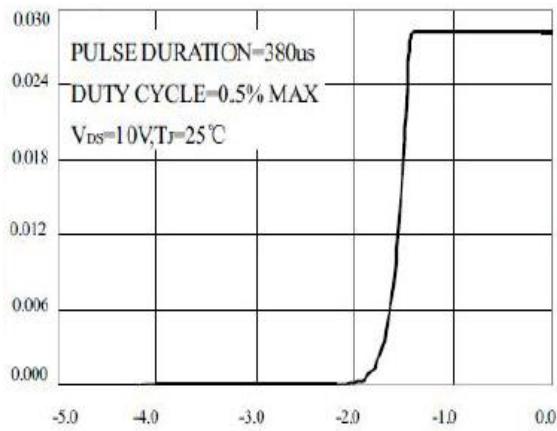


Figure 6 Typical Transfer Characteristics

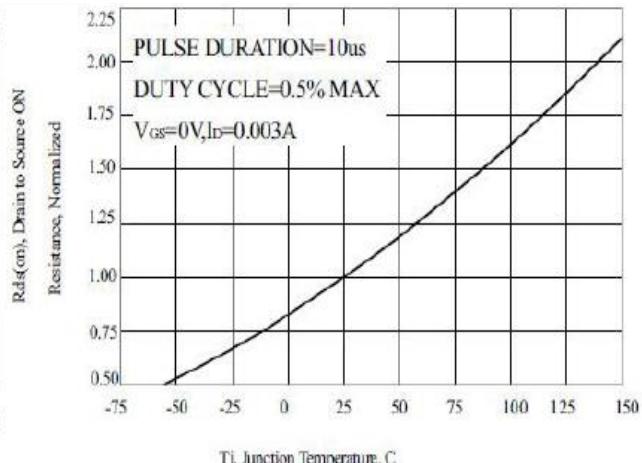


Figure 7 Typical Drain to Source ON Resistance vs Junction Temperature

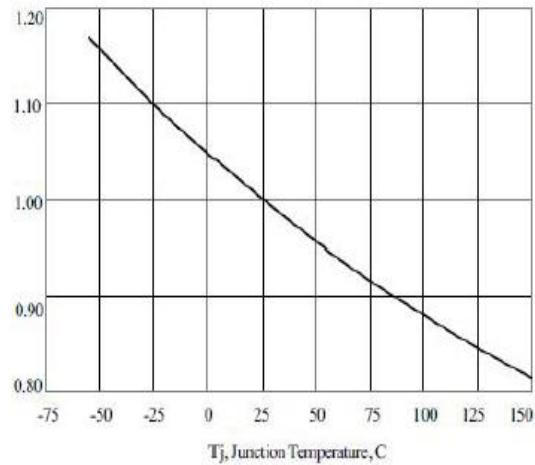


Figure 8 Typical Threshold Voltage vs Junction Temperature

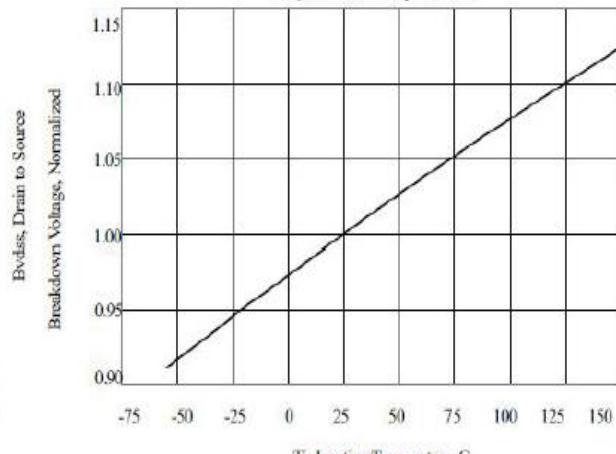


Figure 9 Typical Breakdown Voltage vs Junction Temperature

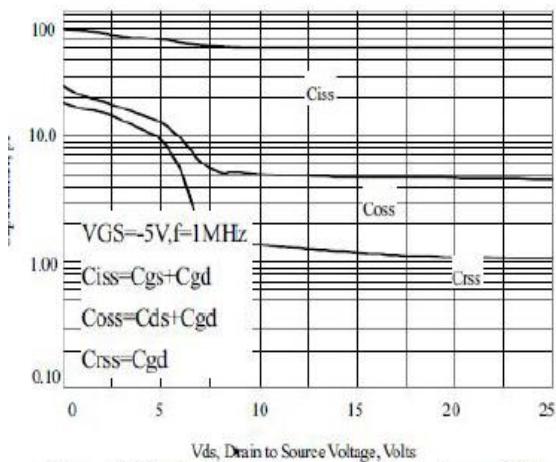


Figure 10 Typical Capacitance vs Drain to Source Voltage

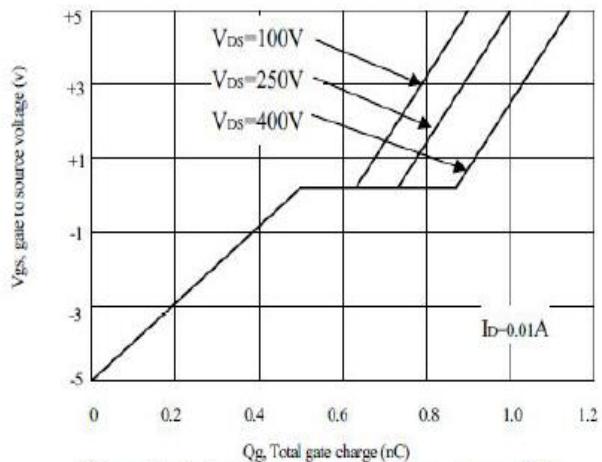


Figure 11 Typical Gate Charge vs Gate to Source Voltage

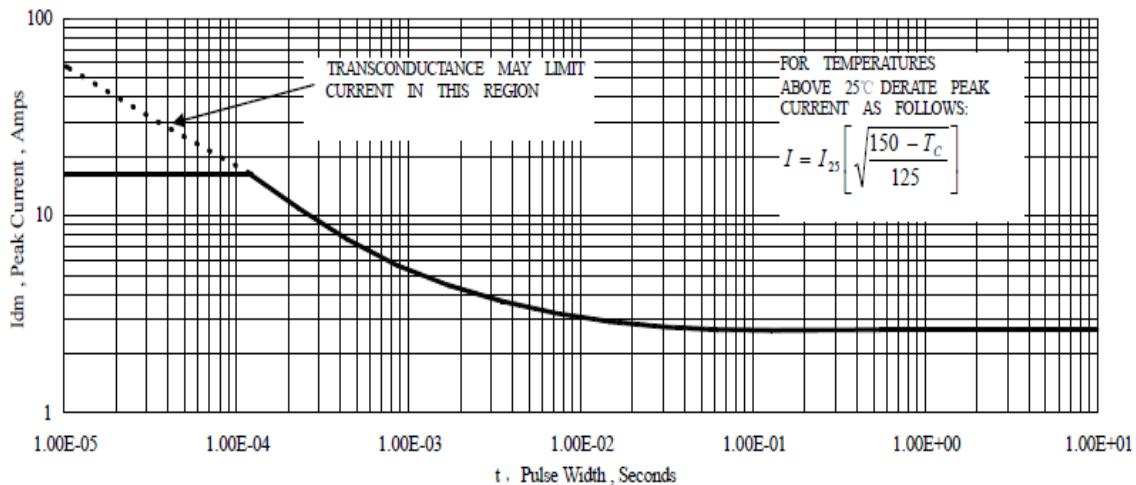


Figure 6 Maximum Peak Current Capability

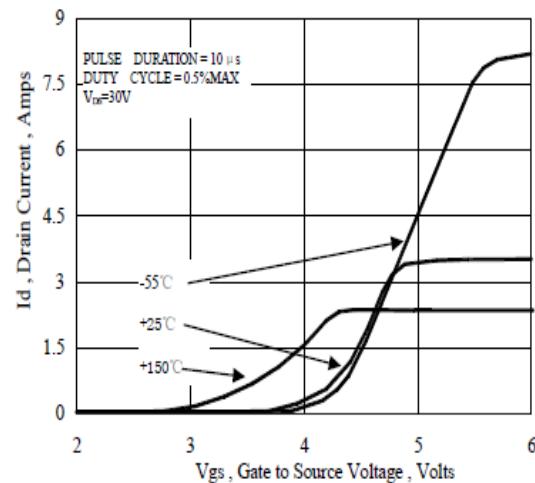


Figure 7 Typical Transfer Characteristics

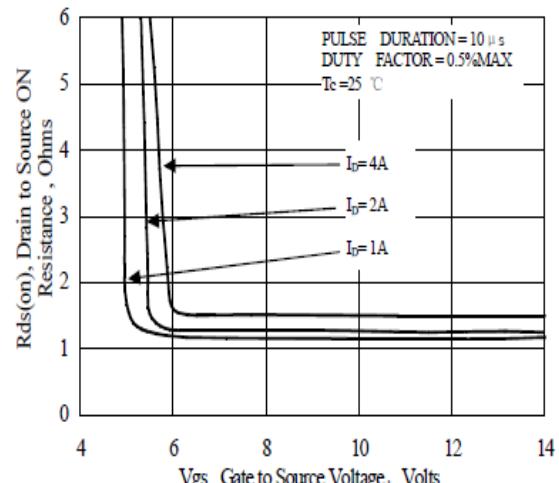


Figure 8 Typical Drain to Source ON Resistance vs Gate Voltage and Drain Current

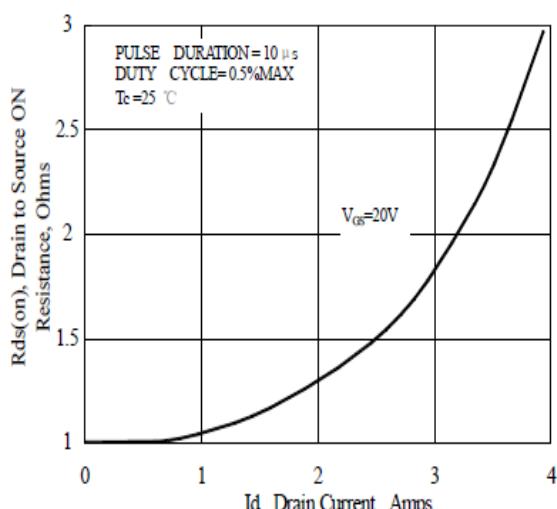


Figure 9 Typical Drain to Source ON Resistance vs Drain Current

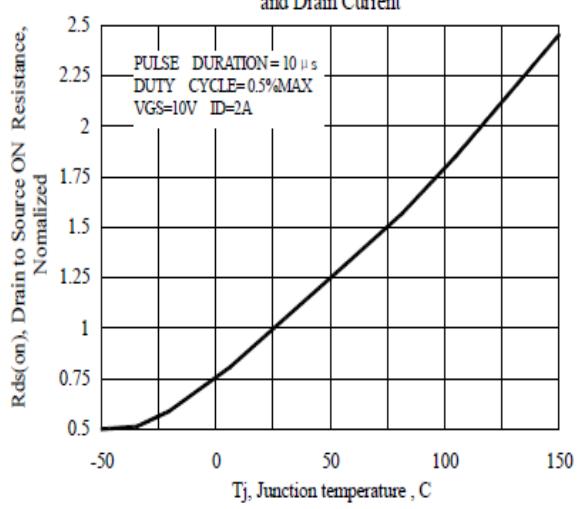
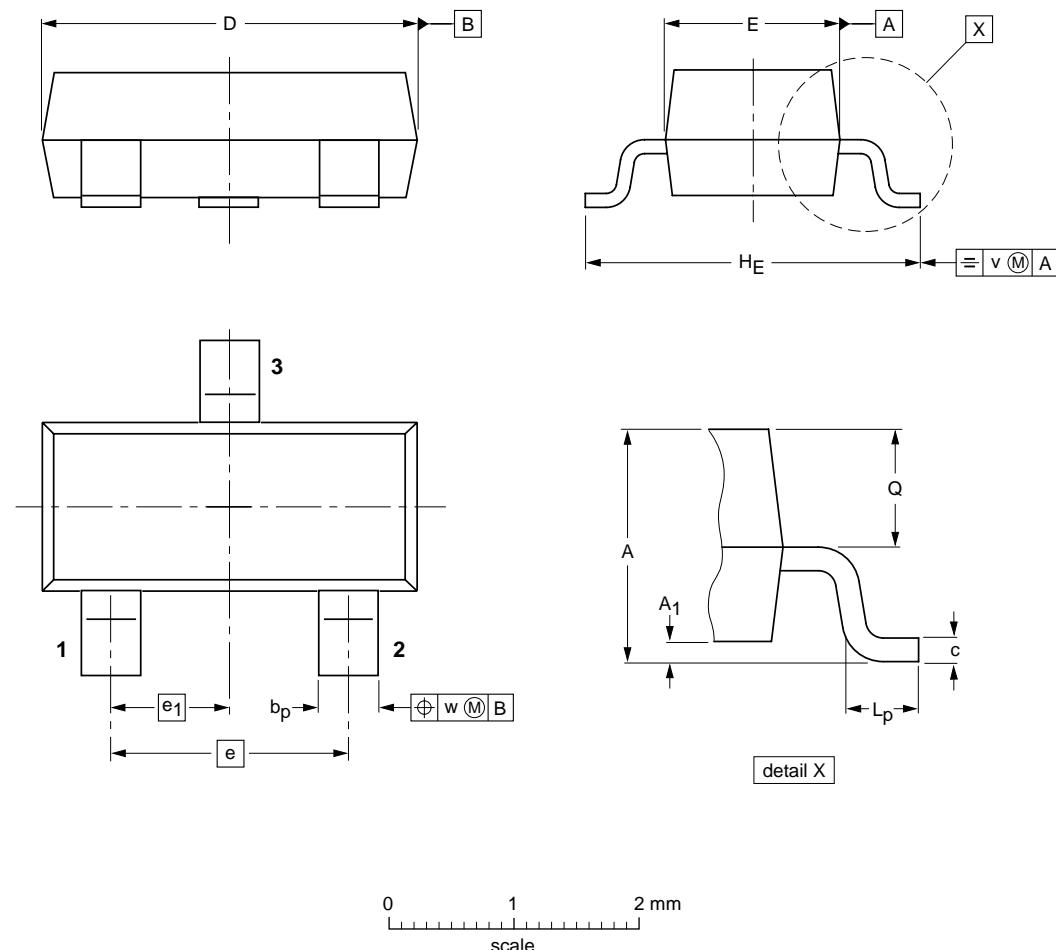


Figure 10 Typical Drian to Source on Resistance vs Junction Temperature

■ SOT-23


DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max.	b _p	c	D	E	e	e ₁	H _E	L _p	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1